



**BESI Datacon 2200 evo
Multi-chip die bonder
SN 950 2218 2199
Vintage 2010**

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SN 950 2218 2199
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located Nijmegen the Netherlands

The Datacon 2200 evo high-accuracy multi-chip die bonder provides the ultimate flexibility for die attach as well as for flip chip applications. Equipped with integrated dispenser, 12" wafer handling, automatic tool changer, and application specific tooling, the Datacon 2200 evo is prepared for present and future processes and products.

Key Features

High Performance at High Accuracy

Highest accuracy $\pm 10 \mu\text{m}$ @ 3 Sigma ($7 \mu\text{m}$ on request)
High productivity, low cost-of-ownership
Up to 4 working heads in one machine

Multi-Chip Capability

Single pass production for complex products
Die attach, flip chip, multi-chip in one machine
Epoxy writing & stamping, flux dipping

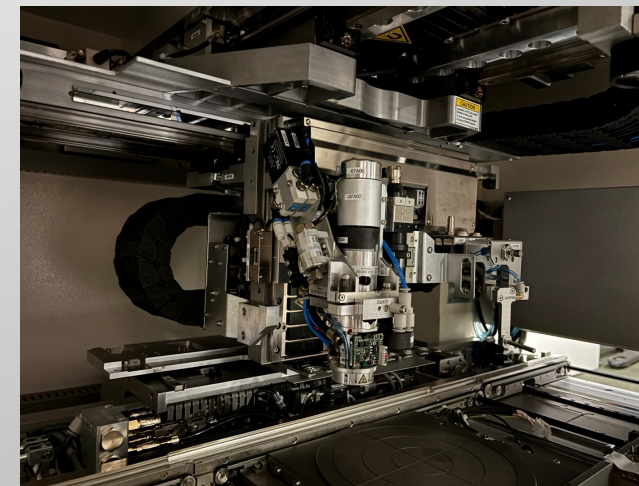
Unbeaten Flexibility

Die pick from wafer, waffle pack, gel pack, feeder
Die place to carrier, boat, substrate, PCB, lead frame, wafer
Hot and cold processes supported: epoxy, soldering, thermo-compression
MCM, SiP, Hybrids



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Specifications

Performance

- X/Y placement accuracy: $\pm 10 \mu\text{m}$ @ 3s
- Theta placement accuracy: $\pm 0.15^\circ$ @ 3s
- Bond Force: 0.5N to 75N programmable

UPH

- Die attach: up to 7,000 UPH/module
- Flip Chip with dipping: up to 2,500 UPH/module
- Flip Chip without dipping: up to 3,200 UPH/module

Bond Heads

- Standard bond head 0° - 360° rotation
- Heated bond head up to 450°C (optional)
- UV Curing (365 nm & 405 nm)

Machine Dimensions

- LxDxH: 1,160 mm x 1,225 mm x 1,750 mm
- Weight: 1,300 kg

Statistics

- Uptime > 98 %
- Yield > 99.95 %

Wafer

- Die size Die Attach: 0.17 mm - 50 mm
- Die size Flip Chip: 0.5 mm - 50 mm
- Die thickness: $>50 \mu\text{m}$ (thinner on request)
- Wafer size: 4" - 12" (SEMI M1)
- Frame size: FF070, FF105, FF108, FF123; automatic change (others on request)

Chip Trays

- Waffle pack / Gel-Pak® 2" x 2" and 4" x 4"
- JEDEC tray on request

Substrates and Carriers

- FR4, ceramic, BGA, flex, boat, lead frame, waffle pack
- Gel-Pak®, JEDEC tray, odd-shape substrates
- Substrate working range: 13" x 8" (325 mm x 200 mm)

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